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Title: **JP62072496A2: SOLDER ALLOY**

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Country: **JP Japan**

Kind: **A**

Inventor(s): **AKIYAMA MITSUO**

Applicant/Assignee: **MATSUO HANDA KK**



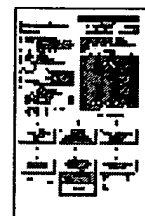
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Application Number: **JP1985000210950**

IPC Class: **B23K 35/26; C22C 11/00; C22C 13/00;**

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Abstract:



**Purpose:** To inexpensively provide a solder alloy having a broad width of m.p. with the decreased amt. of Ag to be used by using a component compounded with a specific ratio each of Sn, Bi and Ag and in some cases, C and consisting of the balance Pb for the solder alloy component.

**Constitution:** The effect of preventing the silver dissolving is synergistically improved and the content of Ag is decreased by making combination use of Bi and Ag. The m.p. is adjusted by the content of Bi. The preventiveness of the silver dissolving is considerably increased by the addition of Cu. Namely, Sn which is the essential component of the solder alloy is incorporated at 20W90% at which the silver dissolving is effectively prevented and the m.p. is increased to prevent the deterioration of the adhesiveness. Bi is incorporated therein at 1W30wt% to provide the effect of making the combination use of Bi and Ag and to prevent the deterioration of the mechanism strength. Ag is incorporated at 0.2W2.0wt% which is the min. limit to provide the effect of making the combination use of Sn-Pb-Ag. Cu is used at 0.1W1.0wt% at which the m.p. is increased and the deterioration of the adhesiveness is obviated. The solder alloy is made wider in the m.p. by the above-mentioned formulation, by which the amt. of the Ag to be used is decreased and the cost is reduced.

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Other Abstract: none

Info:

Foreign References:

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